



JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY CO., LTD

## SOT-523 Plastic-Encapsulate MOSFETs

**CJ4153** N-Channel 20-V(D-S) MOSFET

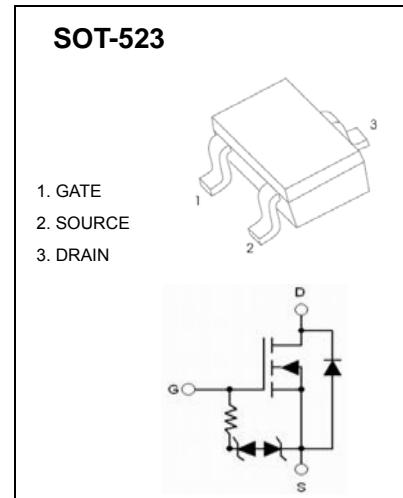
### FEATURE

- Low  $R_{DS(on)}$  Improving System Efficiency
- Low Threshold Voltage ,1.5V Rated
- ESD Protected Gate
- Pb-Free Packages are Available

### APPLICATIONS

- Load/Power Switches
- Power Supply Converter Circuits
- Battery Management
- Portables like Cell Phones, PDAs, Digital Cameras, Pagers,etc

### MARKING: X



**Maximum ratings (  $T_a=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 6$	
Continuous Drain Current (note 1)	$I_D$	0.915	A
Power Dissipation (note 1)	$P_D$	150	mW
Thermal Resistance from Junction to Ambient (note 1)	$R_{\theta JA}$	833	$^\circ\text{C}/\text{W}$
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55~+150	

**Electrical characteristics (  $T_a=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Gate-source leakage	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 4.5\text{V}$			$\pm 1$	$\mu\text{A}$
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{V}$			100	nA
<b>ON CHARACTERISTICS (note 2)</b>						
Gate-source threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.45		1.1	V
Drain-source on-state resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 600\text{mA}$			570	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 500\text{mA}$			620	
		$V_{\text{GS}} = 1.8\text{V}, I_D = 350\text{mA}$			700	
		$V_{\text{GS}} = 1.5\text{V}, I_D = 40\text{mA}$			9500	
Forward transconductance	$g_{\text{fs}}$	$V_{\text{DS}} = 10\text{V}, I_D = 400\text{mA}$	0.5			S
<b>CHARGES AND CAPACITANCES (note 3)</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		110		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			16		
Reverse Transfer Capacitance	$C_{\text{rss}}$			12		
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 4.5\text{V}, I_D = 200\text{mA}$		1.82		$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$			0.3		
Gate-Drain Charge	$Q_{\text{gd}}$			0.42		
<b>SWITCHING CHARACTERISTICS (note 3,4)</b>						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 10\text{V}, V_{\text{GS}} = 4.5\text{V}$ $R_G = 10\Omega, I_D = 200\text{mA}$		3.7		$\text{ns}$
Rise time	$t_r$			4.4		
Turn-off delay time	$t_{\text{d}(\text{off})}$			25		
Fall time	$t_f$			7.6		
<b>DRAIN-SOURCE DIODE CHARACTERISTICS</b>						
Body diode voltage	$V_{\text{SD}}$	$I_s = 0.2\text{A}, V_{\text{GS}} = 0\text{V}$			1.1	V

**Notes :**

1. Surface mounted on FR4 board using 1 in sq pad size.
2. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$ .
3. Guaranteed by design, not subject to production testing.
4. Switching characteristics are independent of operating junction temperatures.